

# Model Name: EBA23001-10

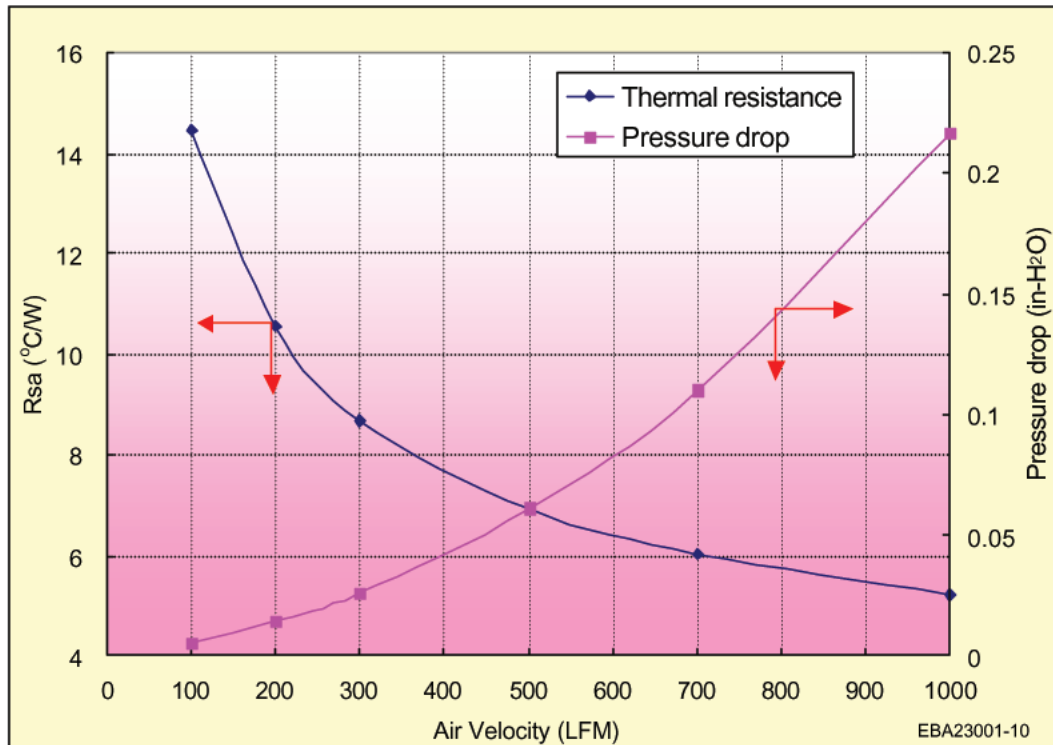
## BGA Heat Sink For 23x23 Chip set

### \*Specification:

1. Material: Aluminum 6063
2. Weight: 6 gm
3. Technology: Extrusion
4. Finish: Black Anodize
5. Heat Sink Dimension:  
22.7\*22.7\*9.8mm
6. Copper package and Moulding compound package available
7. Heat Source size: Uniform



### \*Performance Data:



**AMERICAN THERMAL PRODUCTS**

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